

IN THE CLAIMS:

Cancel claims 22 through 40.

Please amend the claims as follows:

1. (Currently Amended) ~~A method of operating an~~ An automolding system comprising:  
providing a substrate having a surface having a layer of resist on a portion thereof in the automolding system;  
~~preheating the substrate;~~  
~~forming a resist layer;~~  
~~baking the substrate;~~ and  
removing at least a portion of the layer of resist and at least a portion of the contaminants from the substrate using a laser in the automolding system.
2. (Currently Amended) The ~~method of operating an~~ automolding system of claim 1, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.
3. (Currently Amended) The ~~method of operating an~~ automolding system of claim 1, further comprising:  
~~placing the substrate in a mold;~~ and  
encapsulating the substrate in the mold in the automolding system.
4. (Currently Amended) An ~~A method of using~~ a molding system comprising:  
providing a substrate having a surface having a layer of resist on a portion thereof in the molding system;  
~~preheating the substrate;~~  
~~forming a resist layer;~~

baking the substrate; and

removing at least a portion of the layer of resist and contaminants from the substrate using a laser in the automolding system.

5. (Currently Amended) The ~~method of using~~ a molding system of claim 4, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

6. (Currently Amended) The ~~method of using~~ a molding system of claim 4, further comprising:

~~placing the substrate in~~ a mold in the molding system for; and  
encapsulating the substrate.

7. (Currently Amended) A ~~method for operating~~ a system for molding comprising: providing a substrate having a surface having a layer of resist on a portion thereof for molding in the system;

~~preheating the substrate;~~

~~forming a resist layer;~~

~~baking the substrate; and~~

removing at least a portion of the layer of resist and some contaminants from the substrate using a laser in the automolding system.

8. (Currently Amended) The ~~method for operating~~ a system of claim 7, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

9. (Currently Amended) The ~~method for operating~~ a system of claim 7, further comprising:

~~placing the substrate in~~ a mold in the system for; and  
encapsulating the substrate.

10. (Currently Amended) An A method for molding in an automolding system comprising:

placing a substrate having a surface having a layer of resist on a portion thereof in the automolding system;

~~preheating the substrate;~~

~~forming a resist layer;~~

~~baking the substrate;~~ and

removing at least a portion of the layer of resist and at least some of the contaminants from the substrate using a laser in the automolding system.

11. (Currently Amended) The ~~method for molding in an~~ automolding system of claim 10, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

12. (Currently Amended) The ~~method for molding in an~~ automolding system of claim 10, further comprising:

placing the substrate in a mold for; and

encapsulating the substrate in the automolding system.

13. (Currently Amended) In a molding system ~~a method~~ comprising:

placing a substrate having a surface having a layer of resist on at least a portion thereof in the molding system;

~~preheating the substrate;~~

~~forming a resist layer;~~

~~baking the substrate;~~ and

removing at least a portion of the layer of resist and at least some of the contaminants from the substrate using a laser in the automolding system.

14. (Currently Amended) In the molding system of claim 13 ~~the method~~, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

15. (Currently Amended) In the molding system of claim 13 ~~the method~~, further comprising:

~~placing the substrate in~~ a mold in the molding system; ~~and~~  
for encapsulating the substrate.

16. (Currently Amended) A ~~method in~~ a system for molding comprising:  
placing a substrate having a surface having a layer of resist on at least a portion thereof for molding in the system;  
~~preheating the substrate;~~  
~~forming a resist layer;~~  
~~baking the substrate;~~ and  
removing at least a portion of the layer of resist and at least some of the contaminants from the substrate using a laser in the automolding system.

17. (Currently Amended) The ~~method of~~ the system of claim 16, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

18. (Currently Amended) The ~~method of~~ the system of claim 16, further comprising:  
~~placing the substrate in~~ a mold in the system; ~~and for~~  
encapsulating the substrate.

19. (Currently Amended) An A-~~method for using~~ an automolding system having a cleaning apparatus comprising:  
introducing a substrate having a surface having a portion thereof covered with a layer of resist in the automolding system;  
~~preheating the substrate;~~  
~~forming a resist layer;~~  
~~baking the substrate;~~ and

removing at least a portion of the layer of resist and at least some of the contaminants from the substrate using a laser in the automolding system.

20. (Currently Amended) The ~~method for using an~~ automolding system of claim 19, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

21. (Currently Amended) The ~~method for using an~~ automolding system of claim 19, further comprising:

~~placing the substrate in a mold; and for~~  
encapsulating the substrate in the automolding system.

22 through 40 (Canceled)